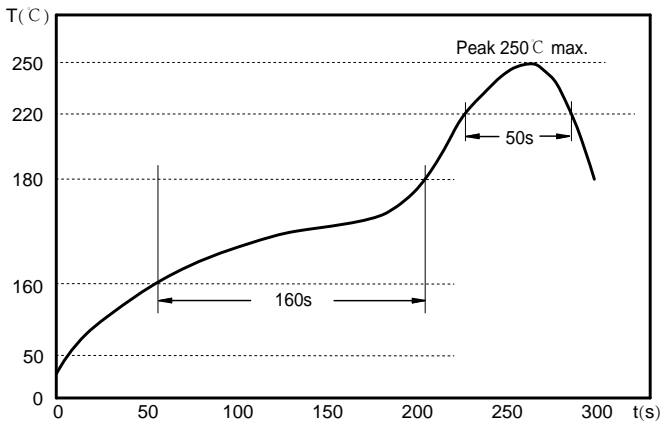






## Soldering Reflow:



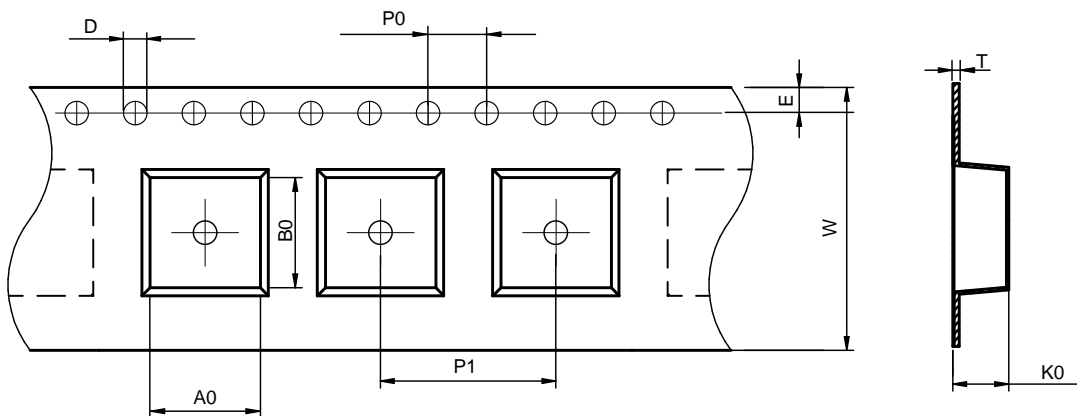
Preheat condition: 160 ~180 °C / 160 sec.

Allowed time above 220 °C : 50 sec.

Max temperature: 250 °C .

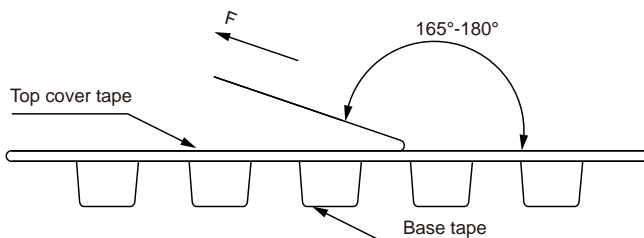
## Packaging Information:

### Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
NRSE8040	9.40±0.1	9.40±0.1	1.50±0.1	4.00±0.1	12.00±0.1	16.00±0.3	4.40±0.1	1.75±0.1	0.40±0.05

### Peel force of top cover tape:

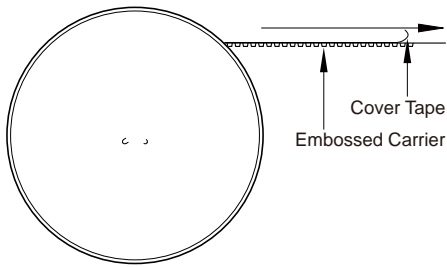


The peel force of top cover tape shall be between 0.03 to 0.98 N

### Product Marking:

Marking	Printing (Inductance)
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Reel Dimension: [mm]



Packaging Quantity: